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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10078243	02/14/2002	257	612	2815	Gurley

****APPLICANTS:** Kripesh Vaidyanathan; iyer Mahadevan; Lim Thiam;
438 2812

****CONTINUING DATA VERIFIED:**
THIS APPLN CLAIMS BENEFIT OF 60/269,500 02/16/2001 Method eliter

**** FOREIGN APPLICATIONS VERIFIED:**

PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no	ALLEN4.001AUS
Verified and Acknowledged Examiner's initials	
TITLE : Process of forming metal surfaces compatible with a wire bonding and semiconductor integrated circuits manufactured by the process	

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drawg.	Figs. Drawg.
			Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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